



## Product/Process Change Notice - PCN 13\_0205 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

*Note: Revised fields are indicated by a red field name. See Appendix B for revision history.*

**PCN Title:** Assembly and Test Transfer of Select 3x3mm LFCSP Products to Amkor Philippines

**Publication Date:** 29-Jul-2014

**Effectivity Date:** 29-Jul-2014 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Updated to include completed Test Correlation Reports and Qualification Results Summary

### Description Of Change

ADI is transferring to subcontractor Amkor Philippines for the assembly and test manufacturing of select 3x3 LFCSP products. The package outline dimensions, wire diameter and die attach epoxy of each product will be maintained. The mold compound is changing from Sumitomo G770 to Sumitomo G700. See BOM attachment for details.

### Reason For Change

ADI is transferring to Amkor Philippines due to the closure of STATS ChipPAC Malaysia at the end of 2014.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

### Impact of the change (positive or negative) on fit, form, function & reliability

The Transfer will have no impact on the form, fit, function and reliability of the devices.

### Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot and the country of origin.

### Summary of Supporting Information

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. Test correlation and validation has been performed per ADI's standard site to site product transfer correlation procedure. See attached qualification reports Summary.

### Supporting Documents

**Attachment 1:** Type: Qualification Results Summary

ADI\_PCN\_13\_0205\_Rev\_A\_Qual Results Summary.pdf

**Attachment 2: Type:** Detailed Change Description

ADI\_PCN\_13\_0205\_Rev\_A\_BOM.xlsx

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**Attachment 3: Type:** Test Correlation Report

ADI\_PCN\_13\_0205\_Rev\_A\_Test Correlatin Report ADA4433-1.pdf

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**Attachment 4: Type:** Test Correlation Report

ADI\_PCN\_13\_0205\_Rev\_A\_Test Correlation Report ADA4432-1.pdf

**For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative**

**Americas:** PCN\_Americas@analog.com

**Europe:** PCN\_Europe@analog.com

**Japan:** PCN\_Japan@analog.com

**Rest of Asia:** PCN\_ROA@analog.com

**Appendix A - Affected ADI Models**

**Existing Parts - Product Family / Model Number (7)**

AD8137 / AD8137WYCPZ-R7	AD8137 / AD8137YCPZ-REEL	AD8137 / AD8137YCPZ-REEL7	ADA4432-1 / ADA4432-1BCPZ-R7	ADA4432-1 / ADA4432-1WBCPZ-R7
ADA4433-1 / ADA4433-1BCPZ-R7	ADA4433-1 / ADA4433-1WBCPZ-R7			

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	25-Nov-2013	15-Apr-2014	Initial Release
Rev. A	29-Jul-2014	29-Jul-2014	Updated to include completed Test Correlation Reports and Qualification Results Summary

Analog Devices, Inc.

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